Final Product Change Notification

202608019F01 : LPC54(S)6xx/LPC54(S)0xx LQFP208 Assembly Site Transfer from SPIL to ATKH

Note: This notice is NXP Company Proprietary.

Issue Date: Sep 30, 2026 **Effective Date:** Dec 29, 2026

Here is your personalized communication about an NXP notification.
For detailed information we invite you to view this notification online

Change Category

[ ]Wafer Fab Process	[ ]Assembly Process	[X]Product Marking	[ ]Test Process	[ ]Design
[ ]Wafer Fab Materials	[X]Assembly Materials	[ ]Mechanical Specification	[ ]Test Equipment	[ ]Errata
[ ]Wafer Fab Location	[X]Assembly Location	[ ]Packing/Shipping/Labeling	[ ]Test Location	[ ]Electrical spec./Test coverage
[ ]Firmware	[ ]Other			

Notification Overview

Description

NXP Semiconductors announces the Assembly site transfer for the LPC54(S)6xxJBD208 and LPC54(S)0xxJBD208 associated with this notification, from the current SPIL Taichung, Taiwan assembly facility to NXP ATKH Kaohsiung, Taiwan assembly facility.

Assembly site transfer was successfully qualified adhering to NXP specifications.

Please see the attached file(s) for additional details.

Reason

Qualification of NXP ATKH Kaohsiung, Taiwan is required for manufacturing flexibility and customer supply assurance.

Identification of Affected Products

Top Side Marking

The assembly site is reflected in the package trace code.

Assembly Site code for SPIL is 'a'.
Assembly Site code for NXP ATKH is 'S'.

Product Availability

Sample Information

Samples are available upon request

Below are the sample part numbers that will be made available.
- LPC54018JBD208
- LPC54S018JBD208
- LPC54618J512BD208
- LPC54S608JBD208/E100

Production

Planned first shipment Jan 15, 2027

Anticipated Impact on Form, Fit, Function, Reliability or Quality

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No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing data sheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification:view online

Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Oct 30, 2026.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

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